3-1658486-3 ACTIVE

MICTOR

TE Internal #: 3-1658486-3

PCB Mount Receptacle, Vertical, Board-to-Board, 84 Position, .8 mm [.031 in] Centerline, Fully Shrouded, Gold, Surface Mount,

Power & Signal, Black

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 84

Centerline (Pitch): .8 mm [.031 in]

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Stackable	No
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	84
Board-to-Board Configuration	Parallel

Electrical Characteristics

Dielectric Withstanding Voltage (Max)	675 VAC
Insulation Resistance	2 ΜΩ
Impedance	100 Ω
Operating Voltage	125 VAC

Body Features

Assembly Process Feature Material	Polyimide Film
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Primary Product Color	Black
Contact Features	
PCB Contact Termination Area Plating Material Thickness	.76 μm[29.9212 μin]
Mating Tab Width	.38 mm[.015 in]
Mating Tab Thickness	.2 mm[.008 in]
Contact Shape & Form	Single Beam
PCB Contact Termination Area Plating Material	Gold
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 μm[29.9212 μin]
Contact Type	Socket
Contact Current Rating (Max)	1.25 A, 9.5 A
Termination Features	
Rectangular Termination Post & Tail Thickness	.15 mm[.006 in]
Rectangular Termination Post & Tail Width	1.77 mm[.07 in]
Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
	Lagatina Dagta
PCB Mount Alignment Type	Locating Posts
Mating Retention	With
Mating Retention	With
Mating Retention Mating Alignment	Without
Mating Retention Mating Alignment PCB Mount Retention	With Without With
Mating Retention Mating Alignment PCB Mount Retention PCB Mount Alignment	With With With With
Mating Retention Mating Alignment PCB Mount Retention PCB Mount Alignment Connector Mounting Type	With With With With
Mating Retention Mating Alignment PCB Mount Retention PCB Mount Alignment Connector Mounting Type Housing Features	With With With Board Mount
Mating Retention Mating Alignment PCB Mount Retention PCB Mount Alignment Connector Mounting Type Housing Features Centerline (Pitch)	With With With Board Mount 8 mm[.031 in]
Mating Retention Mating Alignment PCB Mount Retention PCB Mount Alignment Connector Mounting Type Housing Features Centerline (Pitch) Housing Material	With With With Board Mount 8 mm[.031 in]
Mating Retention Mating Alignment PCB Mount Retention PCB Mount Alignment Connector Mounting Type Housing Features Centerline (Pitch) Housing Material Dimensions	With With With Board Mount 8 mm[.031 in] LCP (Liquid Crystal Polymer)
Mating Retention Mating Alignment PCB Mount Retention PCB Mount Alignment Connector Mounting Type Housing Features Centerline (Pitch) Housing Material Dimensions Connector Height	With With With Board Mount .8 mm[.031 in] LCP (Liquid Crystal Polymer)
Mating Retention Mating Alignment PCB Mount Retention PCB Mount Alignment Connector Mounting Type Housing Features Centerline (Pitch) Housing Material Dimensions Connector Height PCB Thickness (Recommended)	With With With Board Mount .8 mm[.031 in] LCP (Liquid Crystal Polymer)



Assembly Process Feature	Pick and Place Cover
Circuit Application	Power & Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	22
Packaging Type	Box, Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Documents

Product Drawings

MSB0.80RC-ASY84DP,GP,30,VCTY

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_3-1658486-3_M.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_3-1658486-3_M.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_3-1658486-3_M.3d_stp.zip

English

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Product Specifications

Application Specification

English